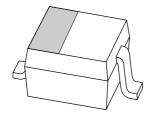
DISCRETE SEMICONDUCTORS

DATA SHEET



BAP64-03 Silicon PIN diode

Product specification Supersedes data of 1999 Aug 27 2004 Feb 11





Silicon PIN diode BAP64-03

FEATURES

- High voltage, current controlled
- RF resistor for RF attenuators and switches
- Low diode capacitance
- Low diode forward resistance
- Low series inductance
- For applications up to 3 GHz.

APPLICATIONS

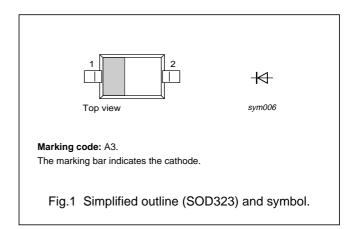
• RF attenuators and switches.

DESCRIPTION

Planar PIN diode in a SOD323 very small plastic SMD package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



ORDERING INFORMATION

TYPE		PACKAGE				
NUMBER	NAME	DESCRIPTION				
BAP64-03	_	plastic surface mounted package; 2 leads	SOD323			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		_	175	V
I _F	continuous forward current		_	100	mA
P _{tot}	total power dissipation	T _s = 90 °C	_	500	mW
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		-65	+150	°C

Silicon PIN diode BAP64-03

ELECTRICAL CHARACTERISTICS

 $T_j = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	forward voltage	I _F = 50 mA	0.95	1.1	V
I _R	reverse current	V _R = 175 V	_	10	μΑ
		V _R = 20 V	_	1	μΑ
C _d	diode capacitance	V _R = 0; f = 1 MHz	0.48	_	pF
		V _R = 1 V; f = 1 MHz	0.35	_	pF
		V _R = 20 V; f = 1 MHz	0.23	0.35	pF
r_D	diode forward resistance	I _F = 0.5 mA; f = 100 MHz; note 1	20	40	Ω
		I _F = 1 mA; f = 100 MHz; note 1	10	20	Ω
		I _F = 10 mA; f = 100 MHz; note 1	2	3.8	Ω
		I _F = 100 mA; f = 100 MHz; note 1	0.7	1.35	Ω
τ∟	charge carrier life time	when switched from I_F = 10 mA to I_R = 6 mA; R_L = 100 Ω ; measured at I_R = 3 mA	1.55	_	μs
L _S	series inductance		1.68	_	nH

Note

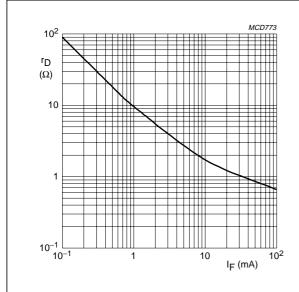
1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th(j-s)}$	thermal resistance from junction to soldering point	120	K/W

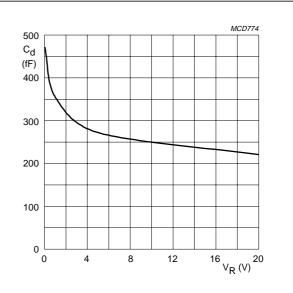
Silicon PIN diode BAP64-03

GRAPHICAL DATA



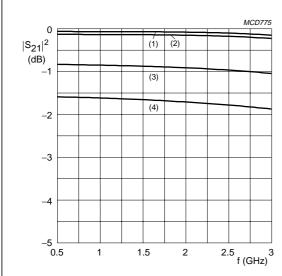
 T_j = 25 °C; f = 100 MHz.

Fig.2 Forward resistance as a function of forward current; typical values.



 $T_j = 25$ °C; f = 1 MHz.

Fig.3 Diode capacitance as a function of reverse voltage; typical values.

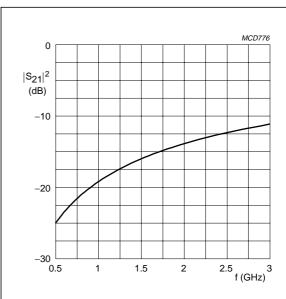


- (1) $I_F = 100 \text{ mA}$.
- (3) $I_F = 1 \text{ mA}.$
- (2) $I_F = 10 \text{ mA}.$
- (4) $I_F = 0.5 \text{ mA}.$

Diode inserted in series with a 50 Ω stripline circuit and biased via the analyzer Tee network.

 $T_{amb} = 25 \, ^{\circ}C.$

Fig.4 Insertion loss ($|S_{21}|^2$) of the diode as a function of frequency; typical values.



Diode zero biased and inserted in series with a 50 Ω stripline circuit. T_{amb} = 25 $^{\circ}C.$

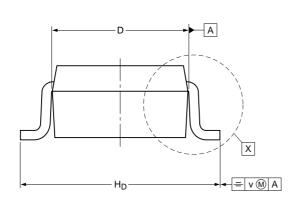
Fig.5 Isolation ($|S_{21}|^2$) of the diode as a function of frequency; typical values.

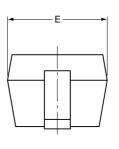
Silicon PIN diode BAP64-03

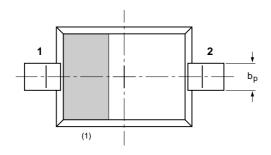
PACKAGE OUTLINE

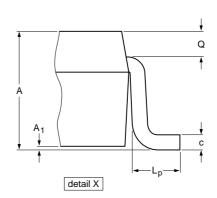
Plastic surface mounted package; 2 leads

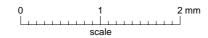
SOD323











DIMENSIONS (mm are the original dimensions)

UNIT	Α	A ₁ max	bp	С	D	E	H _D	Lp	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE		REFERENCES				ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOD323			SC-76			99-09-13 03-12-17

Silicon PIN diode BAP64-03

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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